

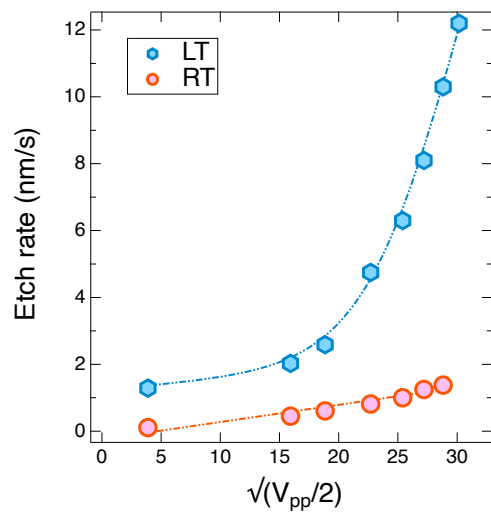


Fig. 1 Etch rate of SiO₂ as a function of square root of $V_{pp}/2$ under the HF plasma at -60 °C (LT) and 20 °C (RT).